

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2630hsc6-lm10#trmpbf

(Engineering Calculation)

SC70

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**TOTAL MASS (g) : 0.010074**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000407	1000000	40400.5546875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.003159	975000	313575.78125		
		Iron (Fe)	7439-89-6	0.000078	24000	7742.61181641		
		Phosphorus (P)	7723-14-0	0.000001	300	99.264251709		
		Zinc (Zn)	7440-66-6	0.000002	700	198.528503418		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003240</b>	<b>1000000</b>	<b>321616.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003408	1000000	338304.46875		
		<b>External Plating Total:</b>				<b>0.003408</b>	<b>1000000</b>	<b>338304.46875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000023	1000000	2283.07788086		
<b>Internal Plating Total:</b>				<b>0.000023</b>	<b>1000000</b>	<b>2283.07788086</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000258	750000	25610.1757812		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000086	250000	8536.7265625		
<b>Die Attach Total:</b>				<b>0.000344</b>	<b>1000000</b>	<b>34146.90625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000151	58000	14988.9023438		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.002314	890000	229697.484375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000130	50000	12904.3525391		
		Carbon Black (C)	1333-86-4	0.000005	2000	496.321228027		
		<b>Encapsulation Total:</b>				<b>0.002600</b>	<b>1000000</b>	<b>258087.0625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000052	1000000	5161.74121094		
					<b>TOTAL MASS (g) :</b>	<b>0.010074</b>		